



Material Content Data Sheet



Sales Product Name		IPD60R750E6		Issued		27. September 2017		
MA#		MA000974350						
Package		PG-TO252-3-341		Weight*		382.37 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.737	0.72	0.72	7157	7157
leadframe	non noble metal	iron	7439-89-6	0.248	0.06		650	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		195	
	non noble metal	copper	7440-50-8	248.124	64.90	64.98	648907	649752
wire	non noble metal	aluminium	7429-90-5	4.211	1.10	1.10	11013	11013
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.681	0.44		4397	
	plastics	brominated resin	-	1.801	0.47		4711	
	organic material	carbon black	1333-86-4	1.921	0.50		5025	
	plastics	epoxy resin	-	16.212	4.24		42398	
	inorganic material	silicondioxide	60676-86-0	98.471	25.75	31.40	257528	314059
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9781	9781
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1331	1331
solder	noble metal	silver	7440-22-4	0.066	0.02		173	
	non noble metal	tin	7440-31-5	0.053	0.01		138	
	non noble metal	lead	7439-92-1	2.522	0.66	0.69	6596	6907
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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